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# *Characterization and Optimization of High Power InGaAs/InP Photodiodes*

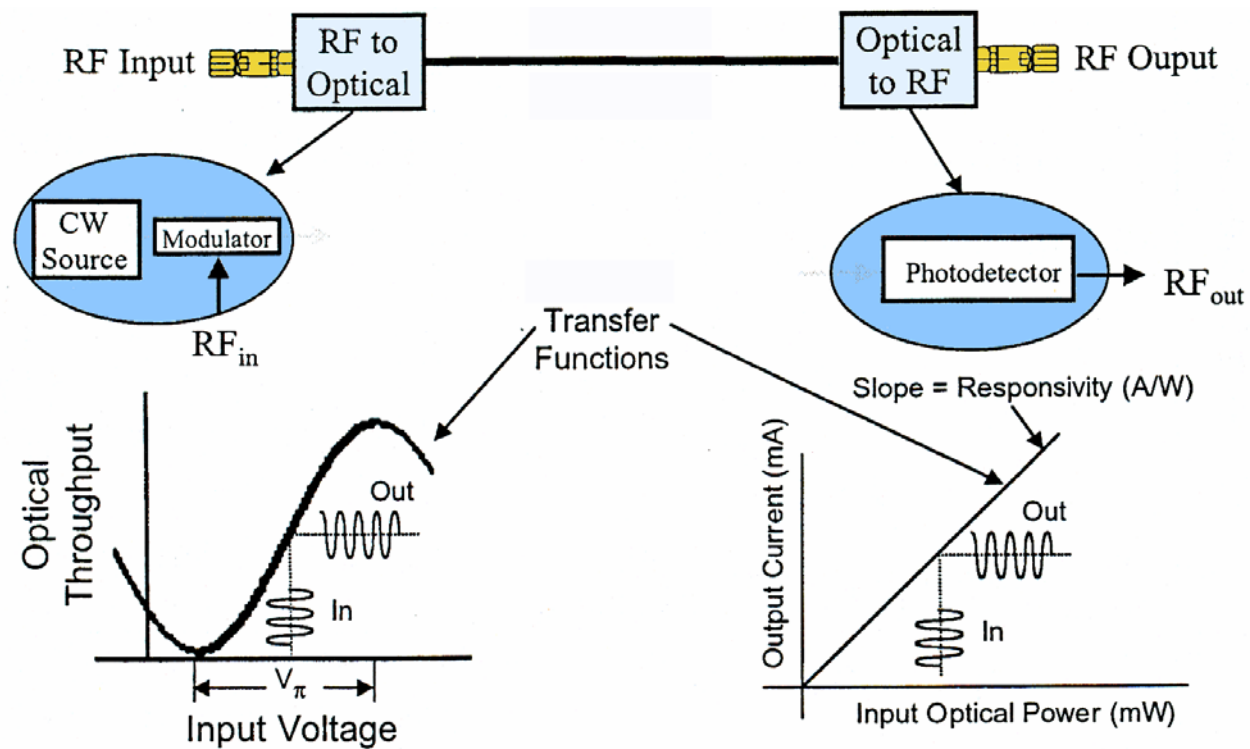
*NUSOD presentation, 2007  
University of Delaware, DE*

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Chen, and Joe C. Campbell*

*Electrical and Computer Engineering  
University of Virginia  
Charlottesville, VA 22904, USA*

Supported by the Naval Research Laboratory

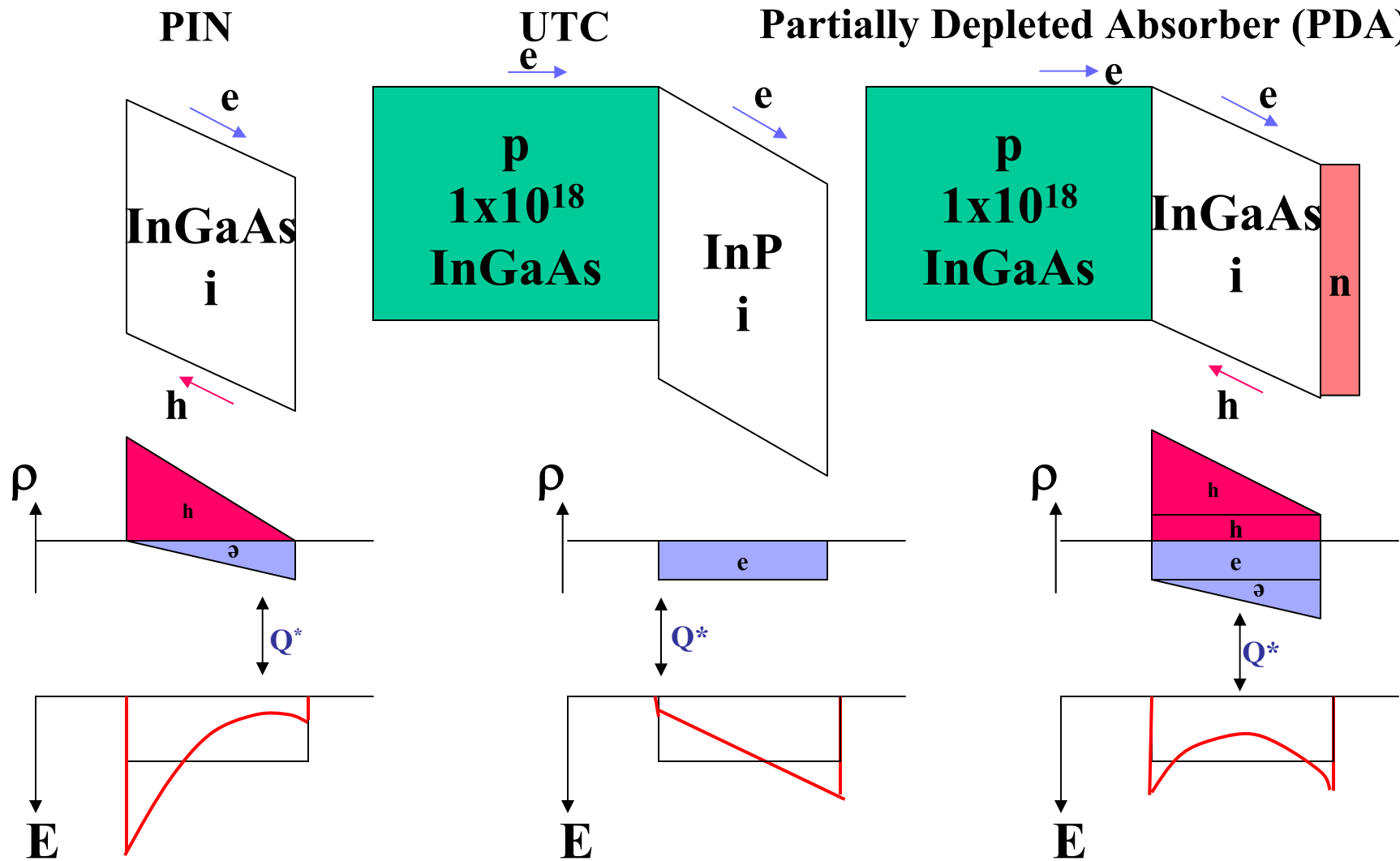
# Analog Fiber Optic Links



$I_{\text{photo}} \uparrow \Rightarrow \text{Gain} \uparrow \text{ Noise} \downarrow \text{ Spur free dynamic range} \uparrow$

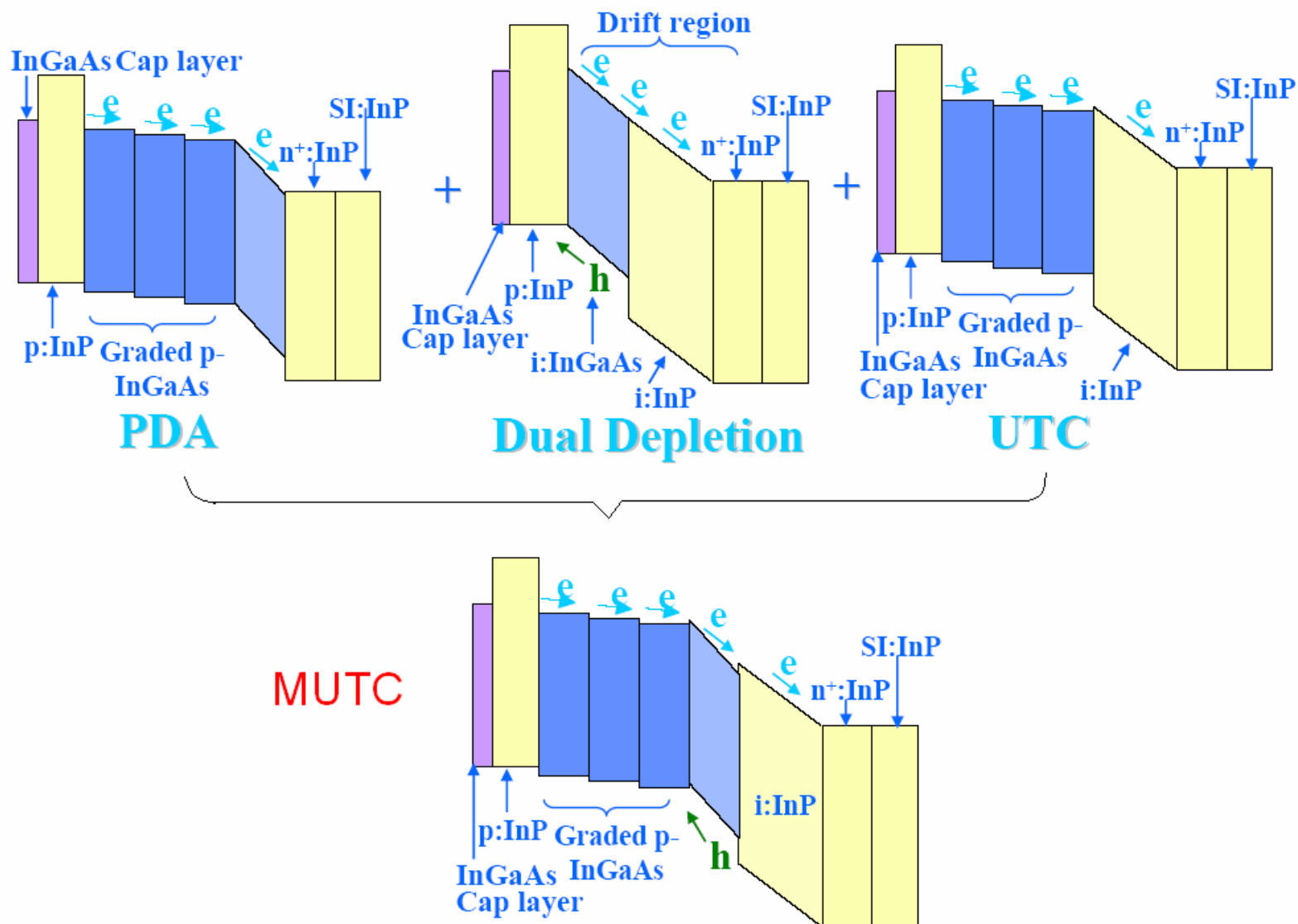


# Schematic Representations of Charge Distribution



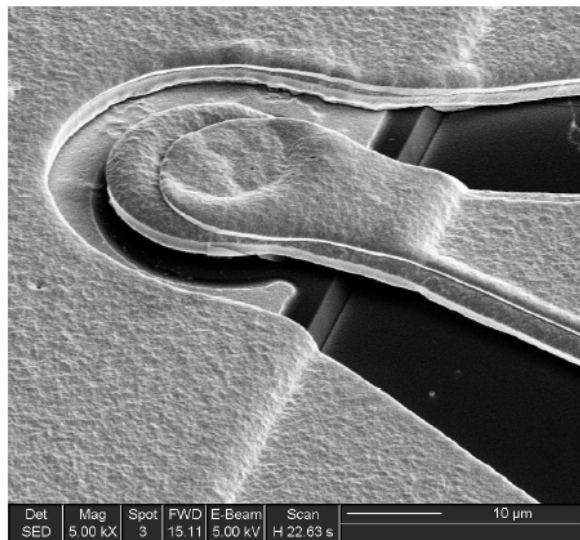
\* $Q^*$ : where the E-field collapses first.

# Evolution of the Epi-structures





# High Power Photodiode with Modified UTC Structure



**Diameter=34 $\mu$ m**

**Series resistance=5.6  $\Omega$**

**Load resistance=50  $\Omega$**

**Capacitance=166fF**

**Saturation Current =  
100mA @ -5V**

**Responsivity=0.75A/W**

**Bandwidth =17GHz**

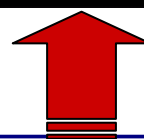
InGaAs, p <sup>+</sup> , Zn, 2.0x10 <sup>19</sup> , 50nm
InP, p <sup>+</sup> , Zn, 3x10 <sup>18</sup> , 1000nm
InGaAs, Zn, 2x10 <sup>18</sup> , 100nm
InGaAs, Zn, 1x10 <sup>18</sup> , 150nm
InGaAs, Zn, 5x10 <sup>17</sup> , 200nm
InGaAs, Zn, 2.5x10 <sup>17</sup> , 200nm
InGaAs, Si, 1.0x10 <sup>16</sup> , 200nm
InGaAsP, Q1.4, undoped, 15nm
InGaAsP, Q1.1, undoped, 15nm
InP, Si, 1.0x10 <sup>16</sup> , 605nm
InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 1000nm
InGaAs, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 20nm
InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 200nm
InP, semi-insulating substrate, Double side polished

} Graded-doped p-absorber

} Intrinsic absorber

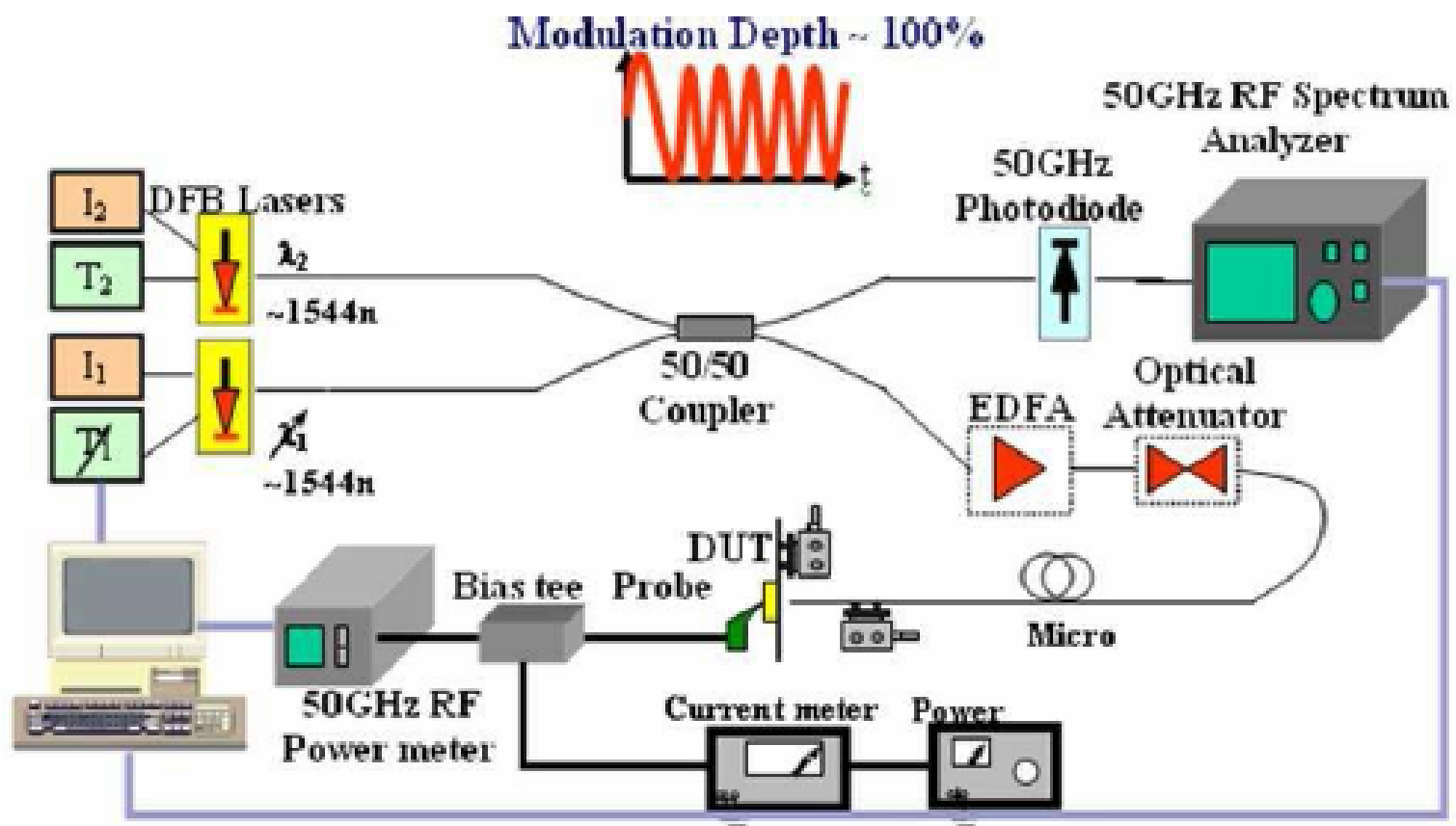
} Graded layer

} Intrinsic collector



Back-illuminated

# Measurement Setup

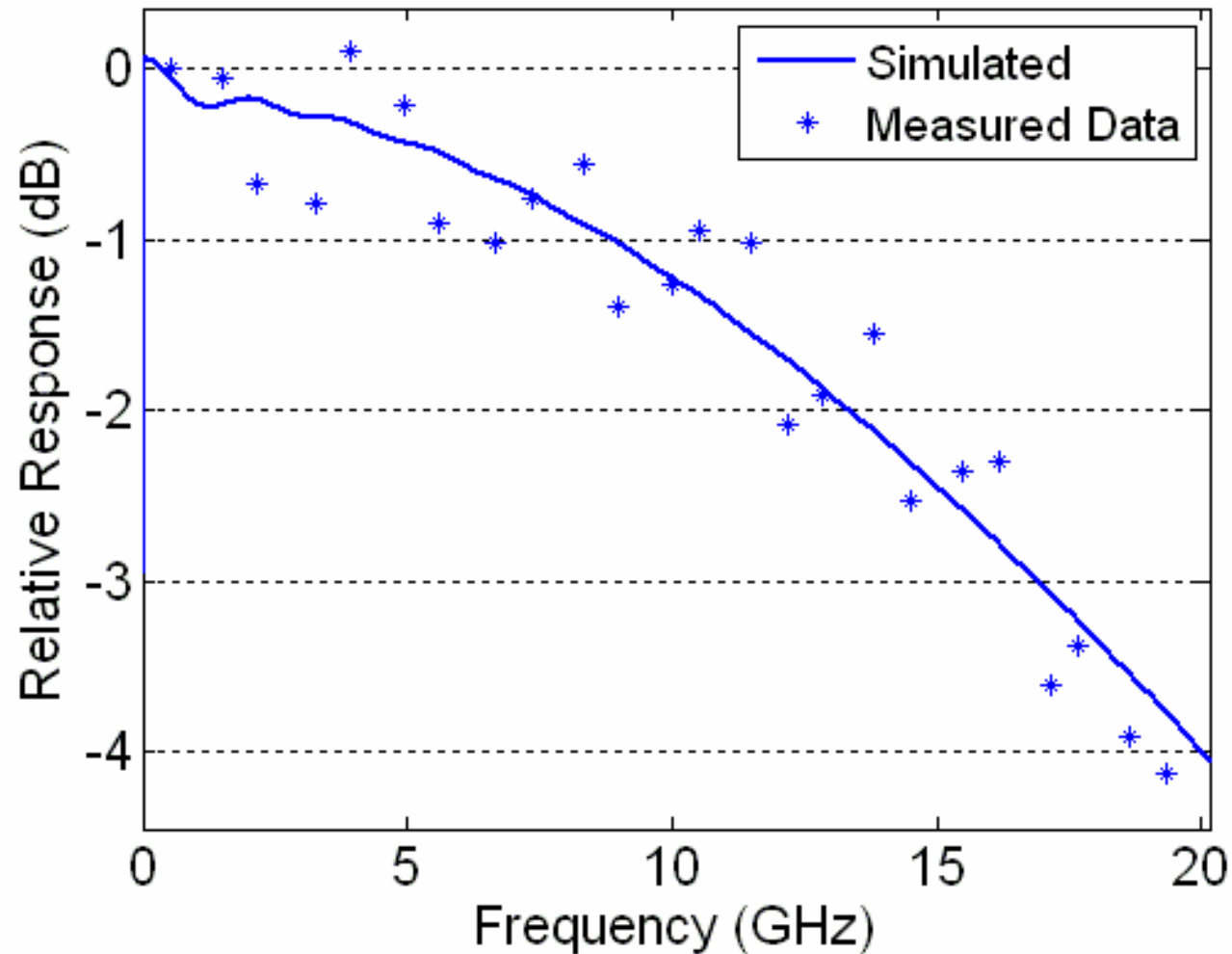


# *Simulation Tools and Saturation Mechanisms*



<u>Mechanism</u>	<u>Included in Present 2-D Model</u>
Space-Charge Electric Fields	Yes
Field Dependent Mobilities	Yes
Generation in Undepleted Regions	Yes
Diffusion	Yes
Trapping	Yes
Heterojunctions	Yes
Thermal Effect	Yes
Loading in the External Circuit	Partial
Transient Temperature Rise	No
Carrier Bleaching	No

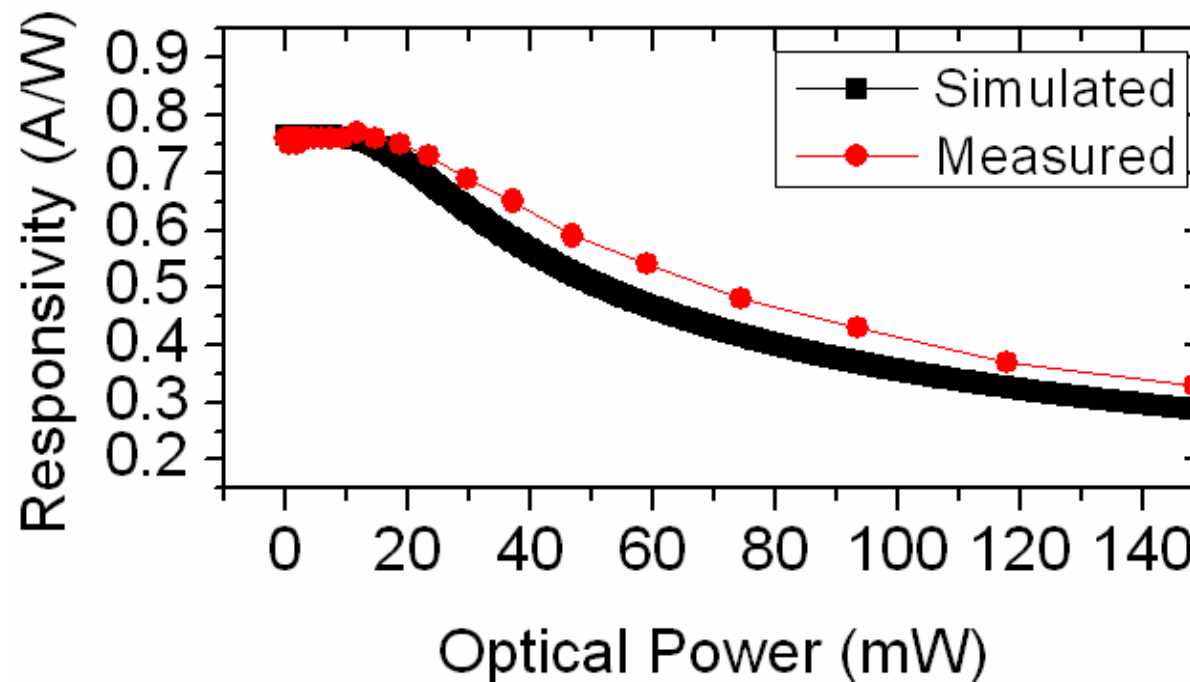
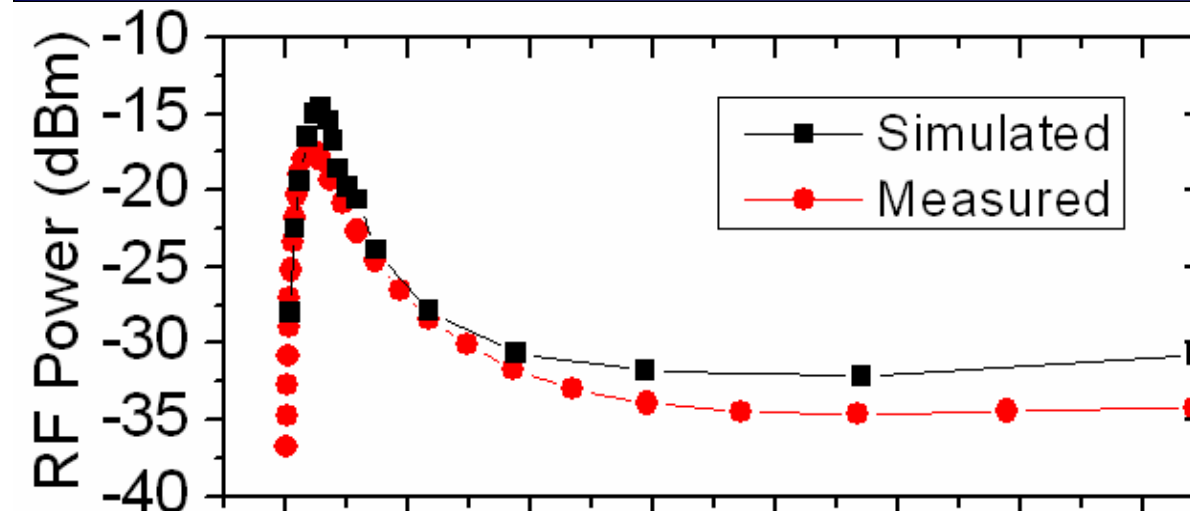
# Bandwidth of the Photodiode



**Frequency response measure at -5V, 30mA.  
RC-limited bandwidth  $f_{RC} = 17\text{GHz}$**



# Saturation Behavior of the Photodiode



Experiment Condition:

Zero bias

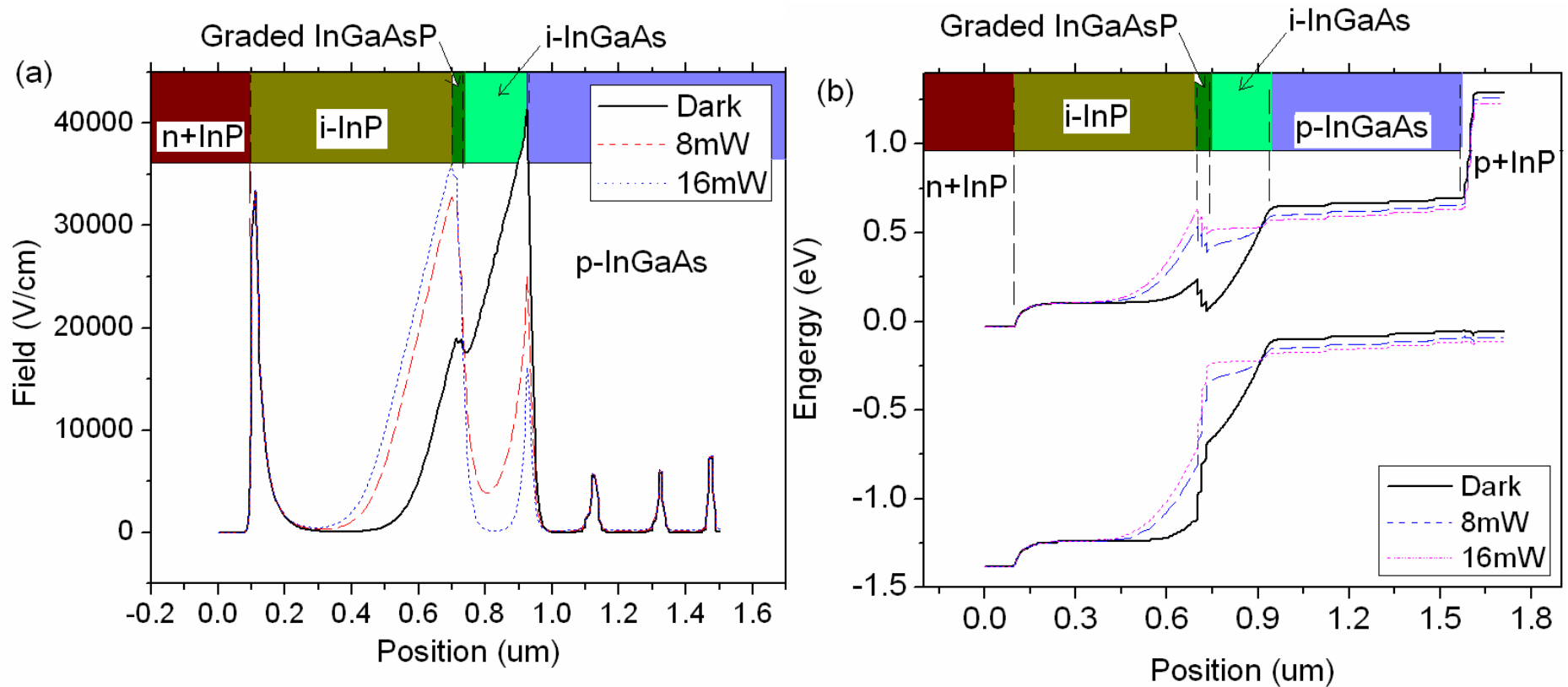
Simulation Includes:

5.6  $\Omega$  series  
resistance

Thermal effect

50  $\Omega$  load resistance not  
included

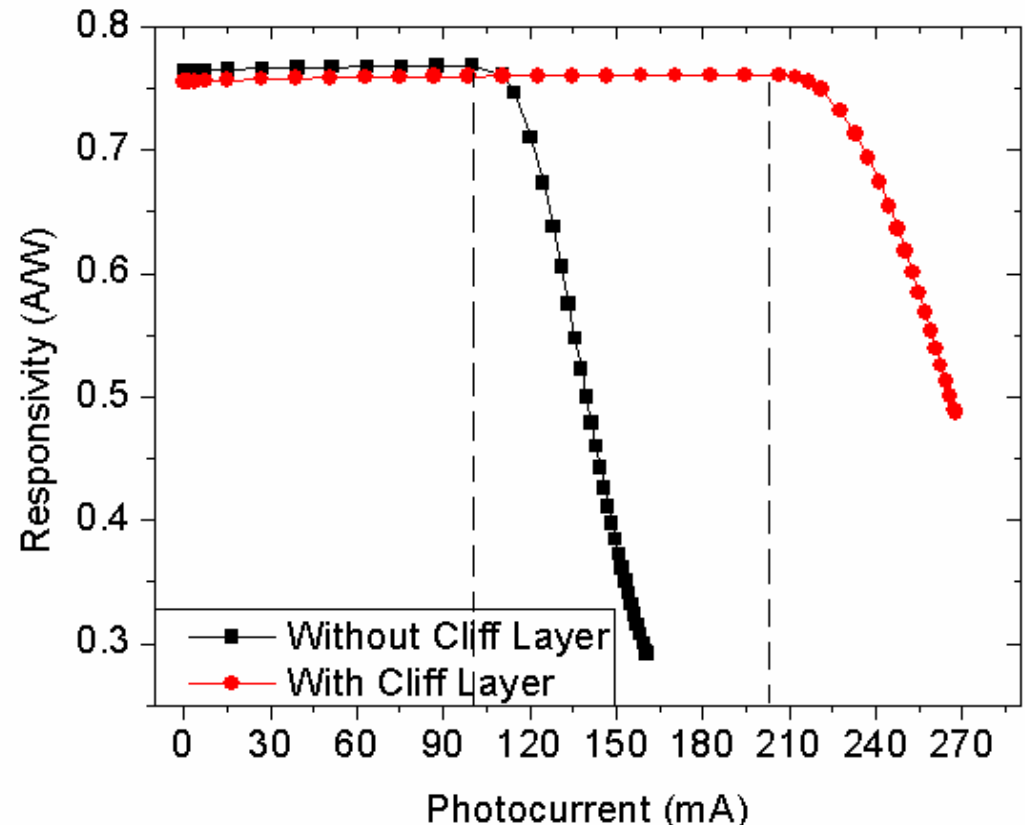
# Saturation



**Electric field in the i-InGaAs reduced, band discontinuity becomes more pronounced**

# Reduced Saturation Effect with Cliff Layer

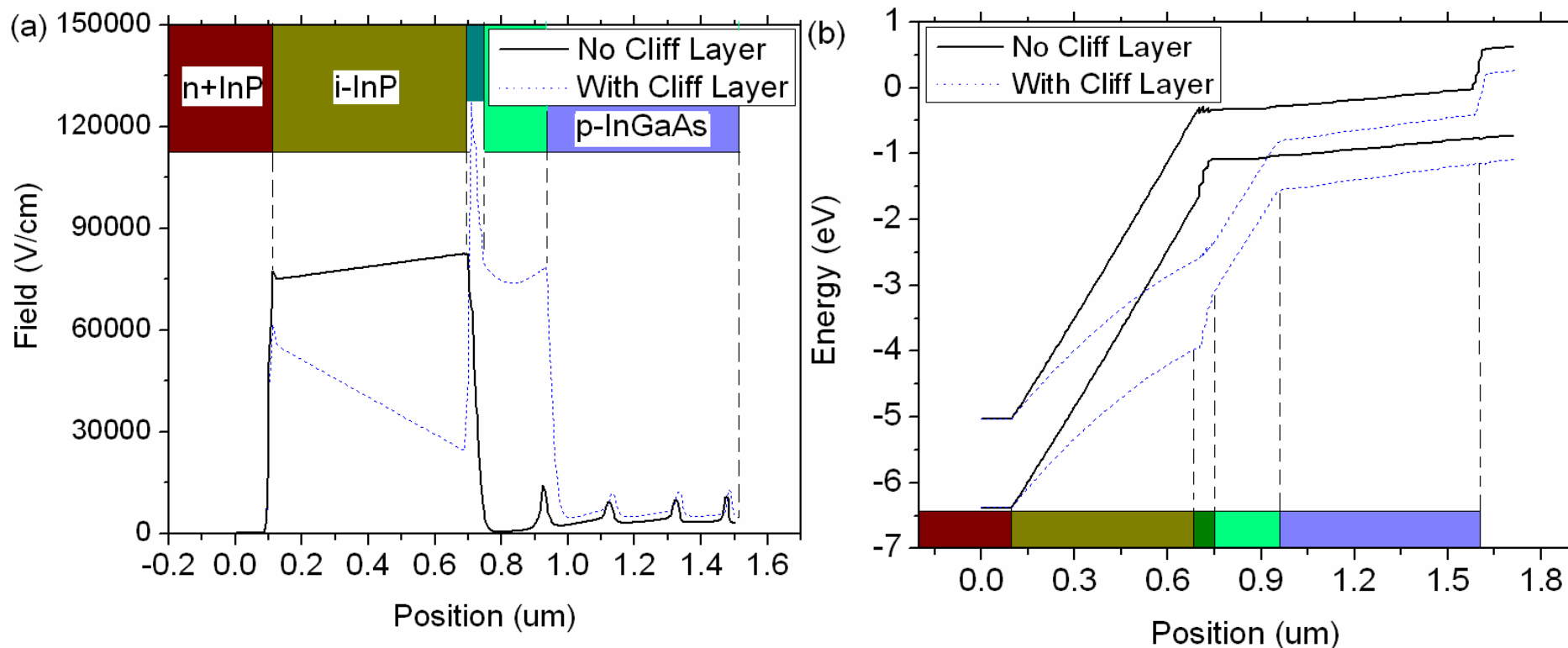
InGaAs, p <sup>+</sup> , Zn, 2.0x10 <sup>19</sup> , 50nm
InP, p <sup>+</sup> , Zn, 1.8x10 <sup>18</sup> , 1000nm
InGaAs, Zn, 2x10 <sup>18</sup> , 100nm
InGaAs, Zn, 1x10 <sup>18</sup> , 150nm
InGaAs, Zn, 5x10 <sup>17</sup> , 200nm
InGaAs, Zn, 2.5x10 <sup>17</sup> , 200nm
InGaAs, Si, 1.0x10 <sup>16</sup> , 200nm
InGaAsP, undoped, Q1.4, 15nm
InGaAsP, undoped, Q1.1, 15nm
InP, Si, 5x10 <sup>17</sup> , 5nm
InP, Si, 1.0x10 <sup>16</sup> , 600nm
InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 1000nm
InGaAs, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 20nm
InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 200nm
InP, semi-insulating substrate, Double side polished



Condition: -5V, T=300K

Moderately doped cliff layer

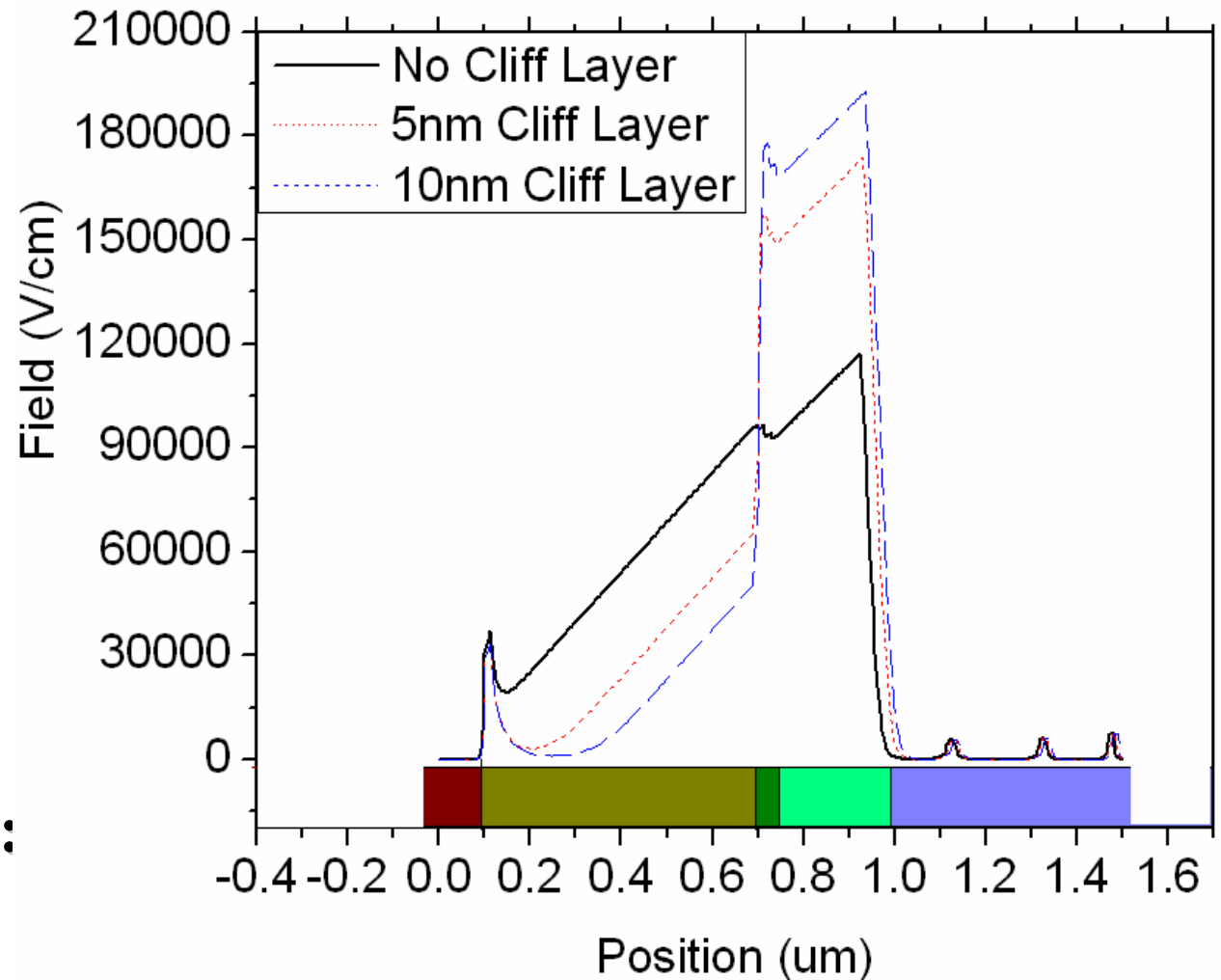
# Role of the Cliff Layer



Condition: -5V, Optical power 235mW

**Electric field enhanced in i-InGaAs absorber.  
 Effect of band discontinuity reduced**

# Optimization of the Cliff Layer



**Optimized cliff layer:**

**Thickness: 5nm**

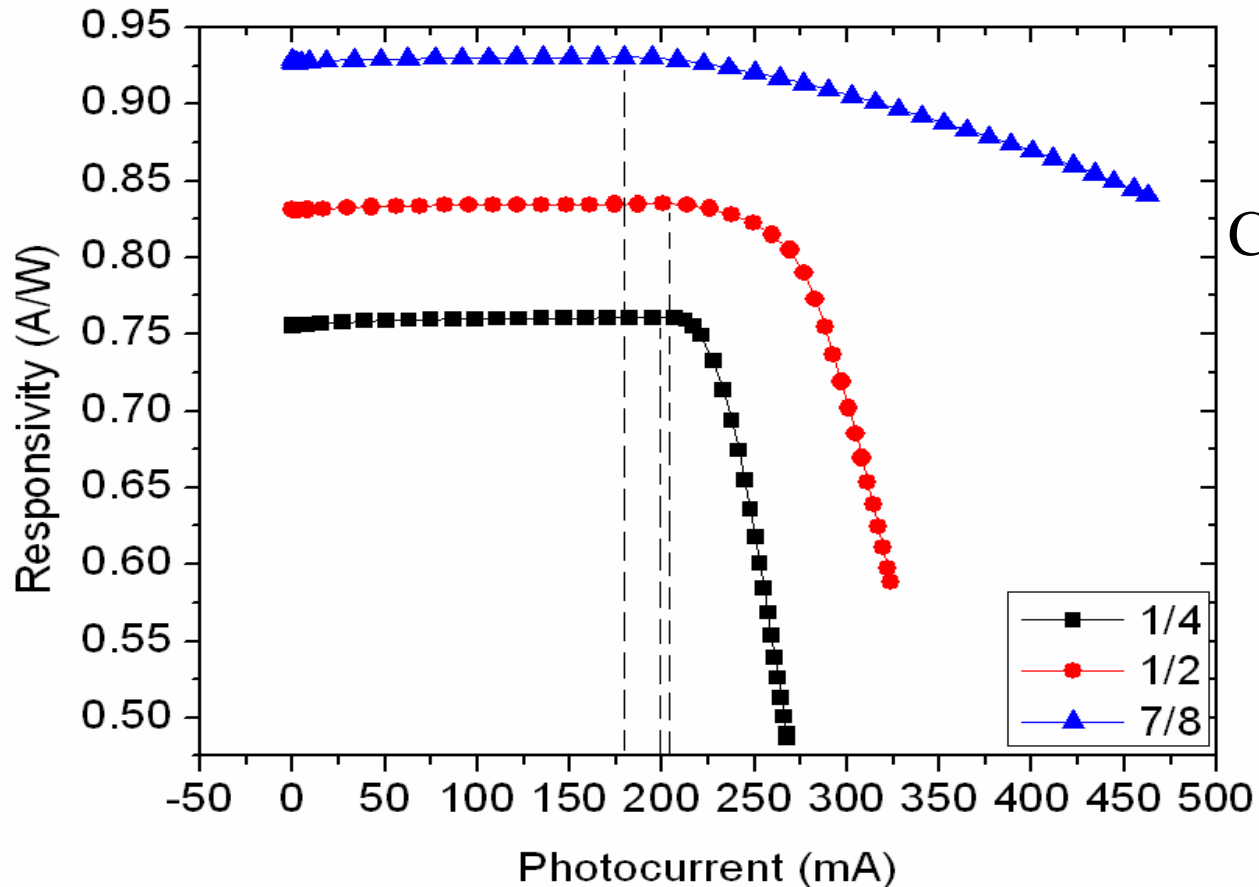
**Doping:  $5 \times 10^{17} \text{ cm}^{-3}$ , n-type**

# Optimization of the Intrinsic Absorber and Collector

$$Fraction = \frac{\text{thickness of i-InGaAs}}{\text{thickness of depletion region}}$$

Depletion Region	InGaAs, p <sup>+</sup> , Zn, 2.0x10 <sup>19</sup> , 50nm	} Intrinsic InGaAs Absorber  } Semi-intrinsic InP Collector
	InP, p <sup>+</sup> , Zn, 1.8x10 <sup>18</sup> , 1000nm	
	InGaAs, Zn, 2x10 <sup>18</sup> , 100nm	
	InGaAs, Zn, 1x10 <sup>18</sup> , 150nm	
	InGaAs, Zn, 5x10 <sup>17</sup> , 200nm	
	InGaAs, Zn, 2.5x10 <sup>17</sup> , 200nm	
	InGaAs, Si, 1.0x10 <sup>16</sup> , 200nm	
	InGaAsP, undoped, O1.4, 15nm	
	InGaAsP, undoped, O1.1, 15nm	
	InP, Si, 5x10 <sup>17</sup> , 5nm	
	InP, Si, 1.0x10 <sup>16</sup> , 600nm	
	InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 1000nm	
	InGaAs, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 20nm	
	InP, n <sup>+</sup> , Si, 1.0x10 <sup>19</sup> , 200nm	
	InP, semi-insulating substrate, Double side polished	

# Optimization of the Intrinsic Absorber and Collector



Conditions:

Bias: -5V

Temperature: 300K

**Degradation current: photocurrent at maximum responsivity**

**Maximum when i-InGaAs =  $\frac{1}{2}$  depletion region**

# Summary

- **Bandwidth of our high power photodiode is RC-limited.**
- **Saturation effect - electric field screening and band discontinuity at the interface of i-InGaAs and i-InP**
- **A cliff layer can be introduced to reduce space charge effect – 2x degradation current**
- **Optimum i-InGaAs fraction = 50% in MUTC structure**